

FMR19N60ES

FUJI POWER MOSFET

Super FAP-E^{3S} series

N-CHANNEL SILICON POWER MOSFET

Features

Maintains both low power loss and low noise Lower R_{DS}(on) characteristic More controllable switching dv/dt by gate resistance Smaller V_{GS} ringing waveform during switching

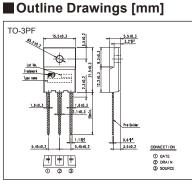
Narrow band of the gate threshold voltage (4.2±0.5V) High avalanche durability

Applications

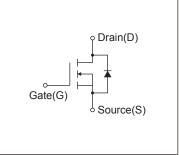
Switching regulators UPS (Uninterruptible Power Supply) **DC-DC converters**

Maximum Ratings and Characteristics

Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)



Equivalent circuit schematic



Description	Symbol	Characteristics	Unit	Remarks
Drain Source Voltage	VDS	600	V	
Drain-Source Voltage	VDSX	600	V	V _{GS} = -30V
Continuous Drain Current	lo	±19	А	
Pulsed Drain Current	IDP	±76	А	
Gate-Source Voltage	Vgs	±30	V	
Repetitive and Non-Repetitive Maximum AvalancheCurrent	lar	19	А	Note*1
Non-Repetitive Maximum Avalanche Energy	Eas	799	mJ	Note*2
Repetitive Maximum Avalanche Energy	Ear	15	mJ	Note*3
Peak Diode Recovery dV/dt	dV/dt	4.8	kV/µs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5
Manimum Davies Disairation	PD	3.13	W	Ta=25°C
Maximum Power Dissipation		150	VV	Tc=25°C
Oneverting and Starage Temperature range	Tch	150	°C	
Operating and Storage Temperature range	Tstg	-55 to + 150	°C	
Isolation Voltage	Viso	2	kVrms	t = 60sec, f = 60Hz

• Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions	Conditions		typ.	max.	Unit	
Drain-Source Breakdown Voltage	BVDSS	I _D =250μA, V _{GS} =0V		600	-	-	V	
Gate Threshold Voltage	Vgs (th)	ID=250µA, VDS=VGS	ID=250µA, VDS=VGS		4.2	4.7	V	
Zero Gate Voltage Drain Current		V _{DS} =600V, V _{GS} =0V	Tch=25°C	-	-	25		
	IDSS	V _{DS} =480V, V _{GS} =0V	Tch=125°C	-	-	250	μA	
Gate-Source Leakage Current	Igss	V _{GS} =±30V, V _{DS} =0V	V _{GS} =±30V, V _{DS} =0V		10	100	nA	
Drain-Source On-State Resistance	RDS (ON)	I _D =9.5A, V _{GS} =10V	I _D =9.5A, V _{GS} =10V		0.31	0.365	Ω	
Forward Transconductance	g fs	ID=9.5A, VDS=25V	ID=9.5A, VDS=25V		16	-	S	
Input Capacitance	Ciss	V _{DS} =25V	V _{DS} =25V		2700	4050	pF	
Output Capacitance	Coss	V _{GS} =0V f=1MHz		-	300	450		
Reverse Transfer Capacitance	Crss			-	17	26		
Turn-On Time	td(on)	V _{cc} =300V V _{cs} =10V I _D =9.5A R ₆ =15Ω		-	45	68	ns	
	tr			-	35	53		
Turn-Off Time	td(off)			-	122	183		
	tf			-	20	30		
Total Gate Charge	QG	V _{cc} =300V I ₀ =19A V _{GS} =10V		-	74	111	nC	
Gate-Source Charge	QGS			-	23	34.5		
Gate-Drain Charge	QGD			-	25	38		
Gate-Drain Crossover Charge	Qsw			-	9	14		
Avalanche Capability	lav	L=1.71mH, Tch=25°C		19	-	-	A	
Diode Forward On-Voltage	Vsd	IF=19A, VGS=0V, Tch=25°C		-	0.90	1.35	V	
Reverse Recovery Time	trr	I _F =19A, V _{GS} =0V		-	0.6	-	μS	
Reverse Recovery Charge	Qrr	-di/dt=100A/µs, Tch=25°C		-	10	-	μC	

Thermal Characteristics

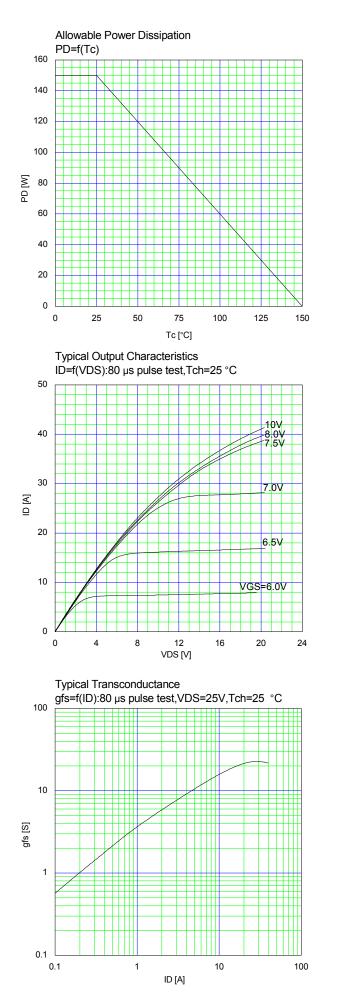
Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to case			0.830	°C/W
	Rth (ch-a)	Channel to ambient			40.0	°C/W

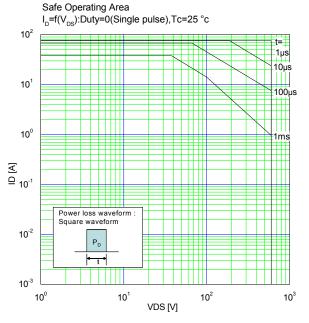
Note *1 : Tch≤150°C

Note 1 : Italia 50 C, IAs=8A, L=22.9mH, Vcc=60V, R_G=50Ω EAs limited by maximum channel temperature and avalanche current. See to 'Avalanche Energy' graph.

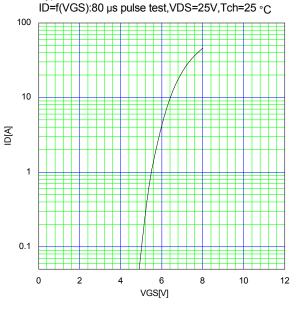
Note *3 : Repetitive rating : Pulse width limited by maximum channel temperature.

See to the 'Transient Themal impeadance' graph. Note *4 : IFS-ID, -di/dt=100A/µs, Vcc≤BVoss, Tch≤150°C. Note *5 : IFS-ID, dv/dt≤4.8kV/µs, Vcc≤BVoss, Tch≤150°C.





Typical Transfer Characteristic



Typical Drain-Source on-state Resistance RDS(on)=f(ID):80 µs pulse test,Tch=25 °C 0.50 VGS=6.0V 81/ 10V 0.45 20\ [U] (uo)SQN 0.35 0.30 0.25 25 30 35 40 0 5 10 15 20 ID [A]

1

0.1

0.00

0.25

0.50

0.75

1.00

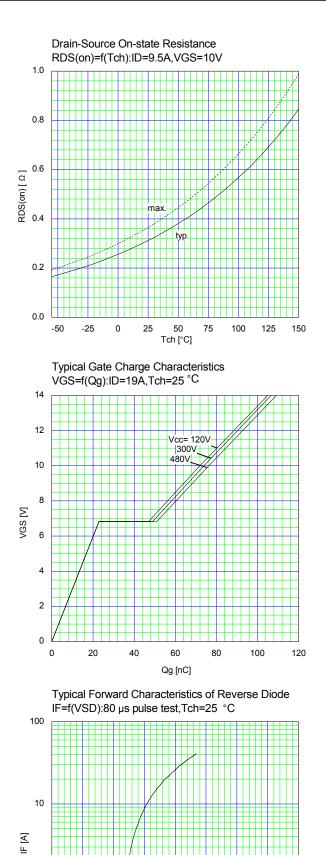
VSD [V]

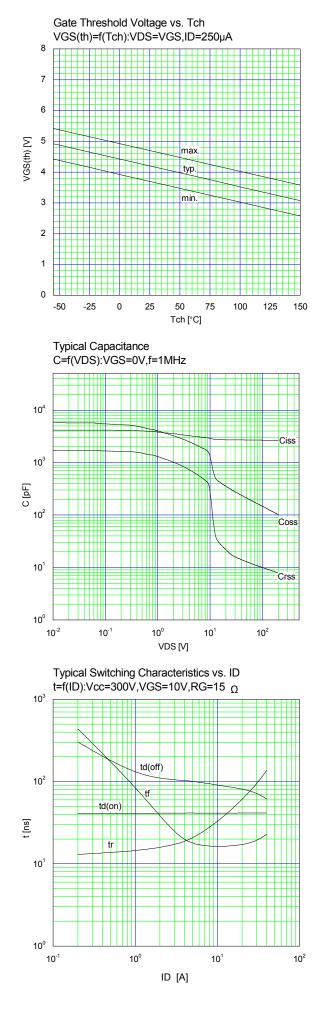
1.25

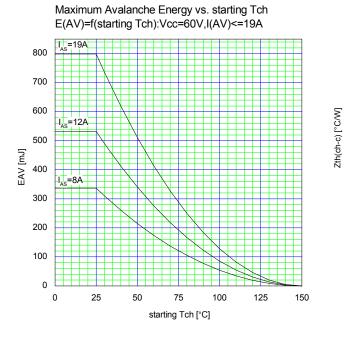
1.50

1.75

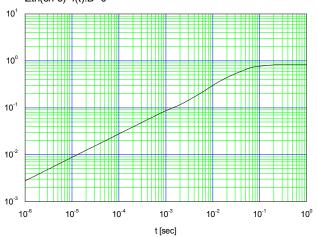
2.00







Maximum Transient Thermal Impedance Zth(ch-c)=f(t):D=0



WARNING

		WARNING		
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